

Product Documentation

CC1F-T1A

**Inverted Mesa AT-Cut
Quartz Crystal Unit
30 MHz – 250 MHz**

2. Product Description

The CC1F-T1A is a high frequency SMT Quartz Crystal Unit that incorporates an Inverted Mesa AT-Cut Quartz Crystal Resonator. The Quartz Crystal Resonator operates under vacuum condition in a hermetically sealed ceramic package with ceramic lid.

Suitable oscillator-circuitries can operate the CC1F-T1A Quartz Crystal Units in fundamental mode in the frequency range of 30 MHz – 250 MHz. For technical assistance for optimizing oscillator-circuitries please contact Micro Crystal under sales@microcrystal.com

2.1. Application Examples

Telemetry
Optical Network
Airborne Equipment
Radio Communications
TCXO, VCTCXO, VCXO
Health Care and Medical

2.2. Ordering Information

Example: CC1F-T1A 155.520 MHz CL: ∞ pF -50/+50ppm TA QI

Code	Operating temperature range
TA (Standard)	-40 to +85°C
TB	-40 to +125°C
TC	-55 to +125°C

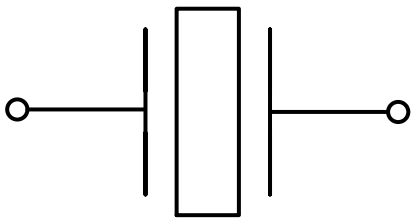
Code	Qualification
QI (Standard)	Industrial Grade
QS	Custom Specification

3. Electrical Characteristics

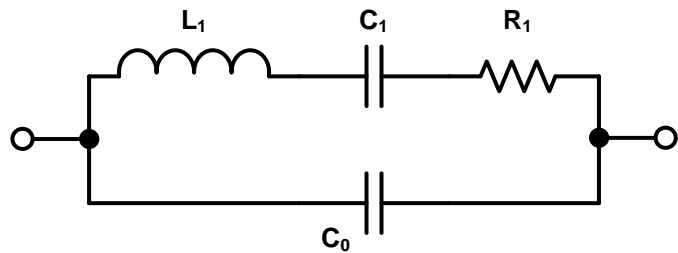
3.1. Equivalent Electrical Model

The Quartz Crystal Unit is a passive component with no polarity. The equivalent circuit of the quartz crystal at its fundamental resonance frequency is represented by the Equivalent Electrical Model:

Electrical Symbol:



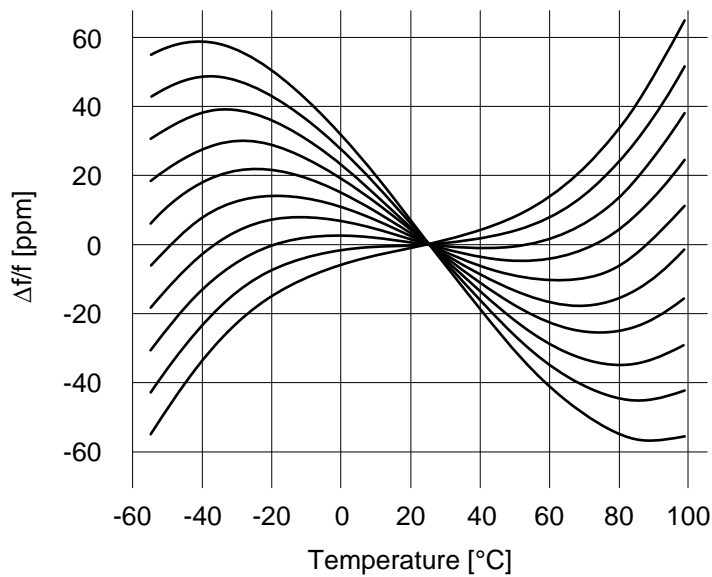
Equivalent Electrical Model:



- L_1 Motional Inductance
- C_1 Motional Capacitance
- R_1 Motional Resistance (ESR)

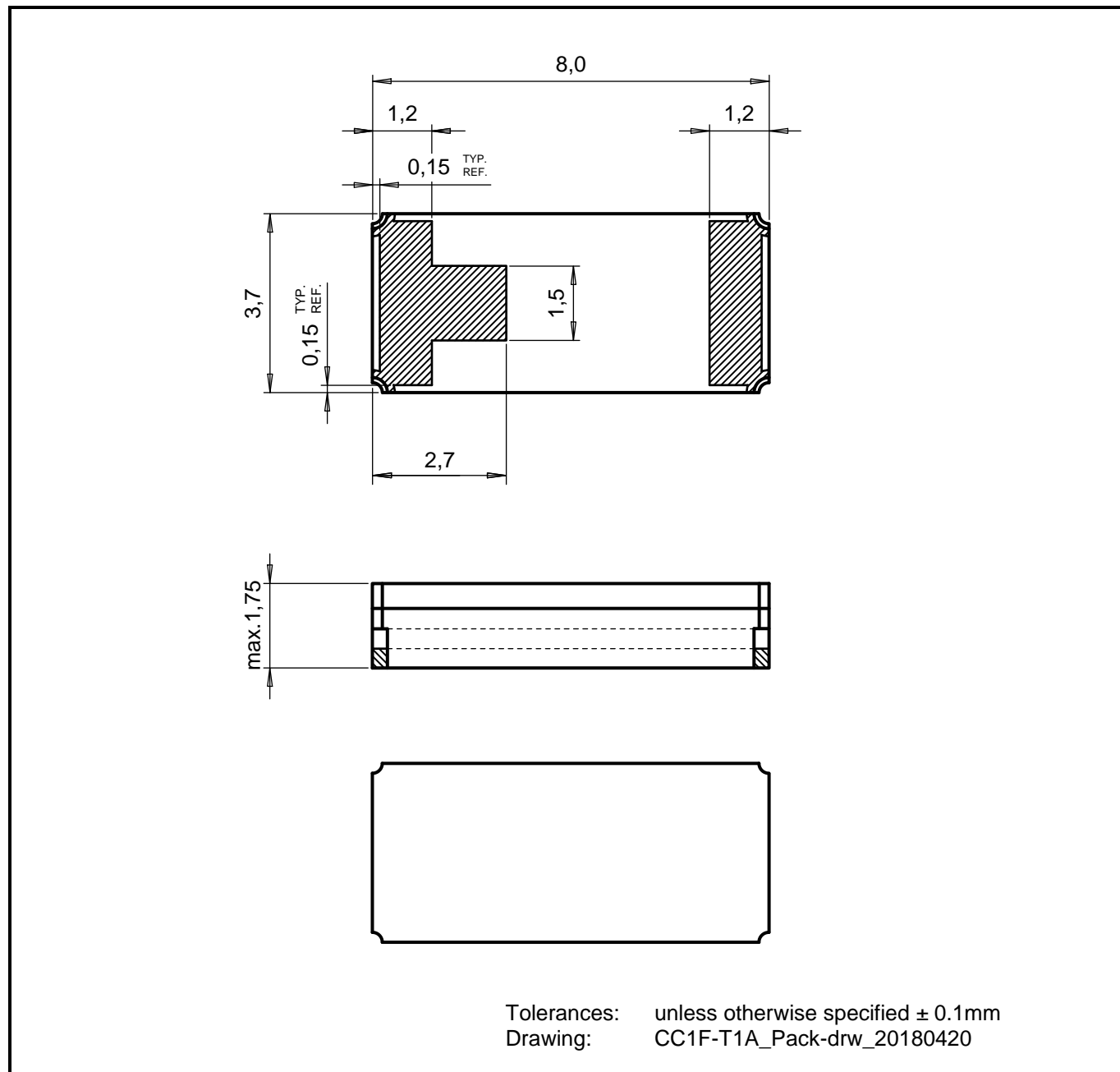
- C_0 Static Capacitance (Shunt capacitance)

3.2. Frequency vs Temperature Characteristics

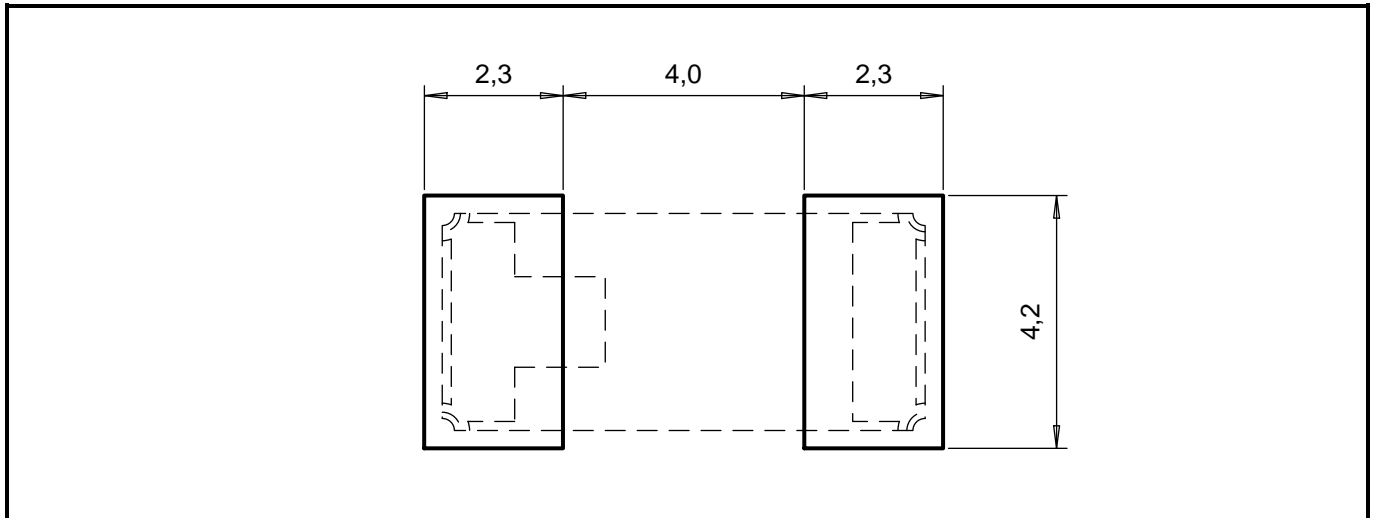


4. Mechanical Properties

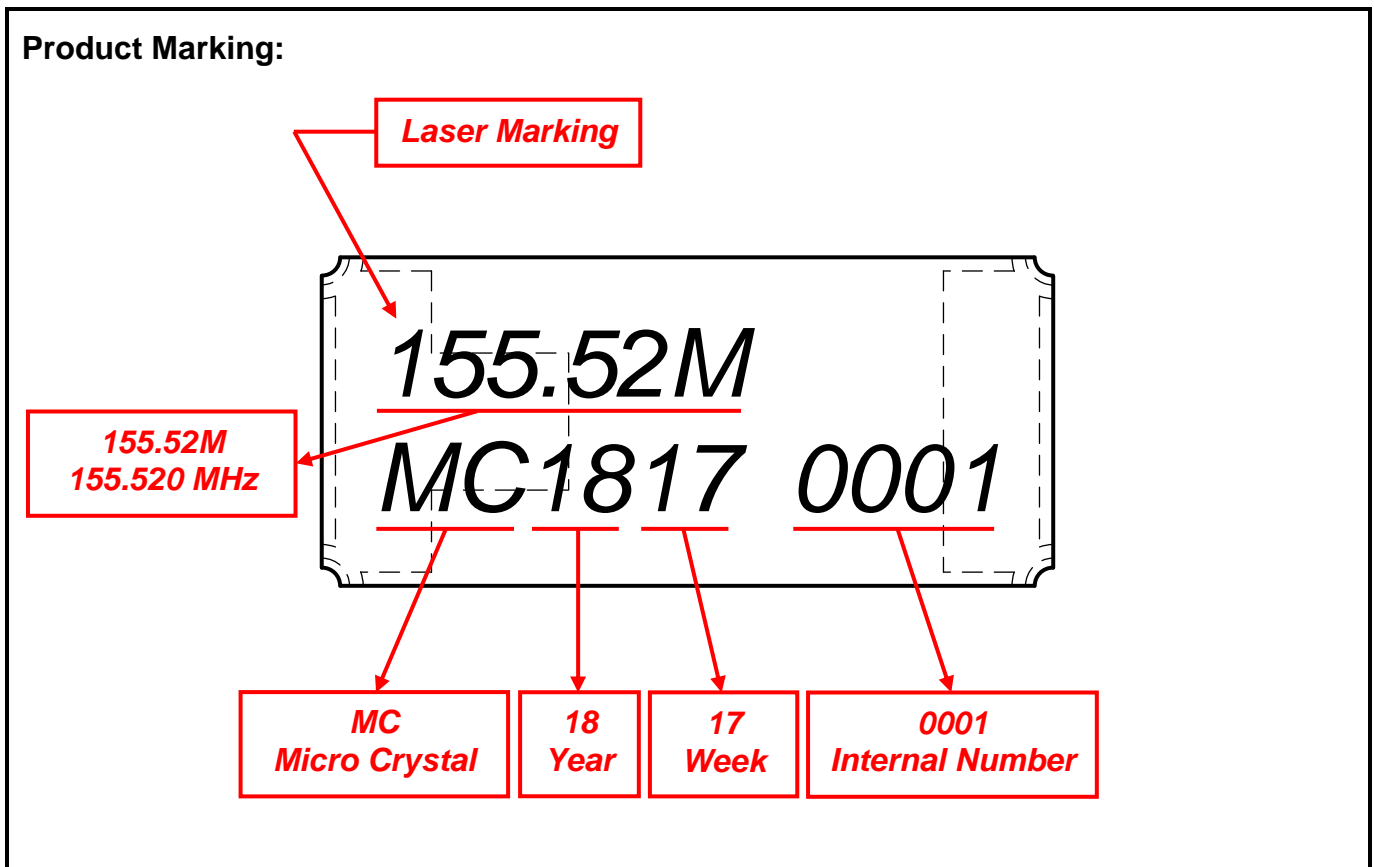
4.1. Package Dimension



4.2. Recommended Solderpad Layout



4.3. Product Marking

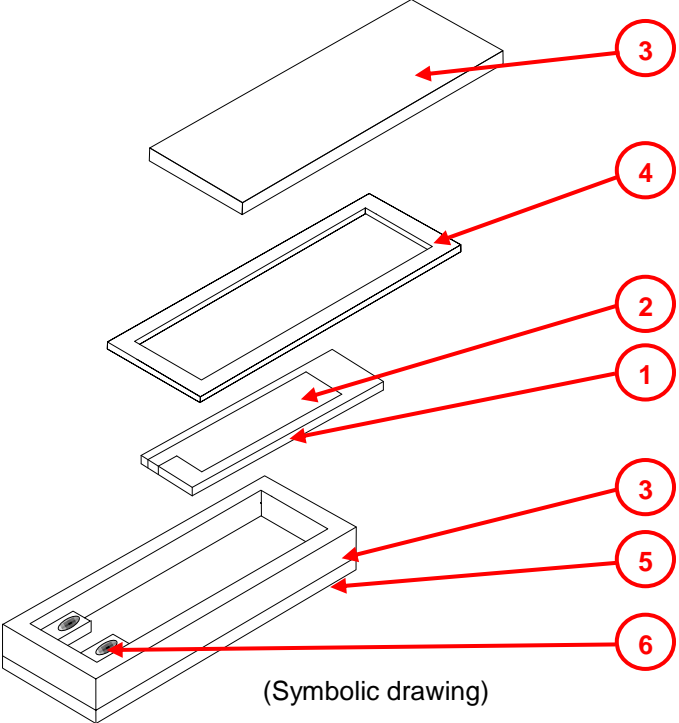


5. Material Composition Declaration & Environmental Information



5.1. Homogenous Material Composition Declaration

Homogenous material information according to IPC-1752 standard

Material Composition CC1F-T1A:



(Symbolic drawing)

No.	Item Component Name	Sub Item Material Name	Material Weight		Substance Element	CAS Number	Comment
			(mg)	(%)			
1	Resonator	Quartz Crystal	0.70	100%	SiO ₂	14808-60-7	
2	Electrodes	Cr+Au	0.01	6%	Cr	7440-47-3	
				94%	Au	7440-57-5	
3	Housing	Ceramic	125.40	100%	Al ₂ O ₃	1344-28-1	
4	Seal	Solder Preform	6.50	80%	Au80 / Sn20	Au: 7440-57-5	
				20%		Sn: 7440-31-5	
5	Terminations	Internal and external terminals	7.10	80%	W	W: 7440-33-7	Tungsten
				15%	Ni	Ni: 7440-02-0	Nickel plating
				5%	Au 0.5 micron	Au: 7440-57-5	Gold plating
6	Conductive adhesive	Silver filled glue	0.29	88%	Ag	Ag: 7440-22-4	
				12%	Glue		
		Unit weight typ. ±10%	140				

5.2. Material Analysis & Test Results

Homogenous material information according to IPC-1752 standard

No.	Item Component Name	Sub Item Material Name	RoHS						Halogen				Phthalates			
			Pb	Cd	Hg	Cr+6	PBB	PBDE	F	Cl	Br	I	BBP	DBP	DEHP	DINP
1	Resonator	Quartz Crystal	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd
2	Electrodes	Cr+Au	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd
3	Housing	Ceramic	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd
4	Seal	Solder Preform	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd
5	Terminations	Int. & ext. terminals	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd
6	Conductive adhesive	Silver filled glue	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd
	MDL	Measurement Detection Limit	2 ppm			5 ppm		50 ppm				0.003%		0.01%		

nd = not detectable

Test methods:

RoHS	Test method with reference to IEC 62321-5: 2013	MDL: 2 ppm (PBB / PBDE: 5 ppm)
Halogen	Test method with reference to BS EN 14582:2007	MDL: 50 ppm
Phthalates	Test method with reference to EN 14372	MDL: 0.003 % (DINP 0.01%)

5.3. Recycling Material Information

Recycling material information according to IPC-1752 standard.

Element weight is accumulated and referenced to the unit weight of 140 mg.

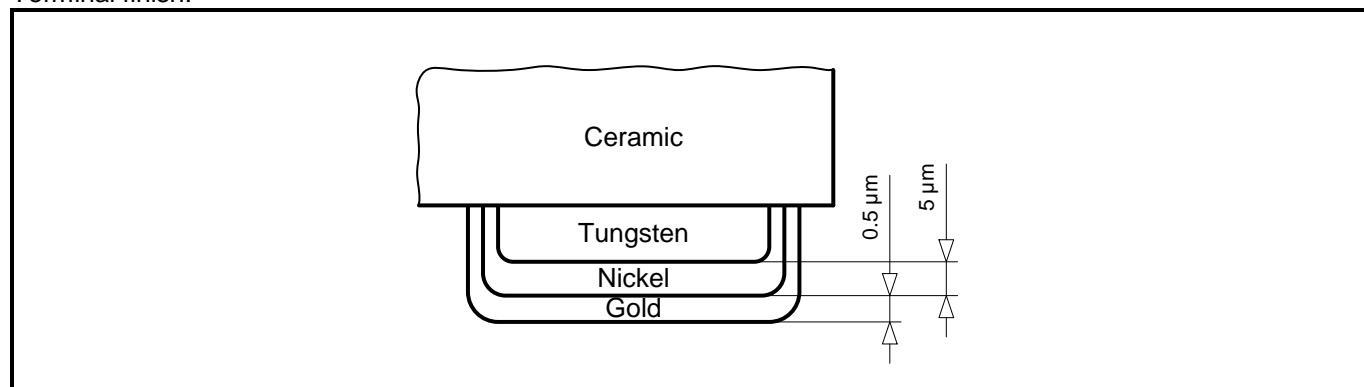
Item Material Name	No.	Item Component Name	Material Weight		Substance Element	CAS Number	Comment
			(mg)	(%)			
Quartz Crystal	1	Resonator	0.70	0.50	SiO ₂	14808-60-7	
Chromium	2	Electrodes	0.0006	0.0004	Cr	7440-47-3	
Ceramic	3	Housing	125.40	89.57	Al ₂ O ₃	1344-28-1	
Gold	2 4 5	Electrodes Seal Terminations	5.56	3.97	Au	7440-57-5	
Tin	4	Seal	1.30	0.93	Sn	Sn: 7440-31-5	
Nickel	5	Terminations	1.07	0.76	Ni	Ni: 7440-02-0	
Tungsten	5	Terminations	5.68	4.06	W	W: 7440-33-7	
Silver	6a	Conductive adhesive	0.26	0.18	Ag	Ag: 7440-22-4	
Glue	6b	Conductive adhesive	0.035	0.025	Glue		
Unit weight (total) typ. ±10%			140	100			

5.4. Environmental Properties & Absolute Maximum Ratings

Package	Description
Ceramic Package	Hermetic ceramic-package, no-leads

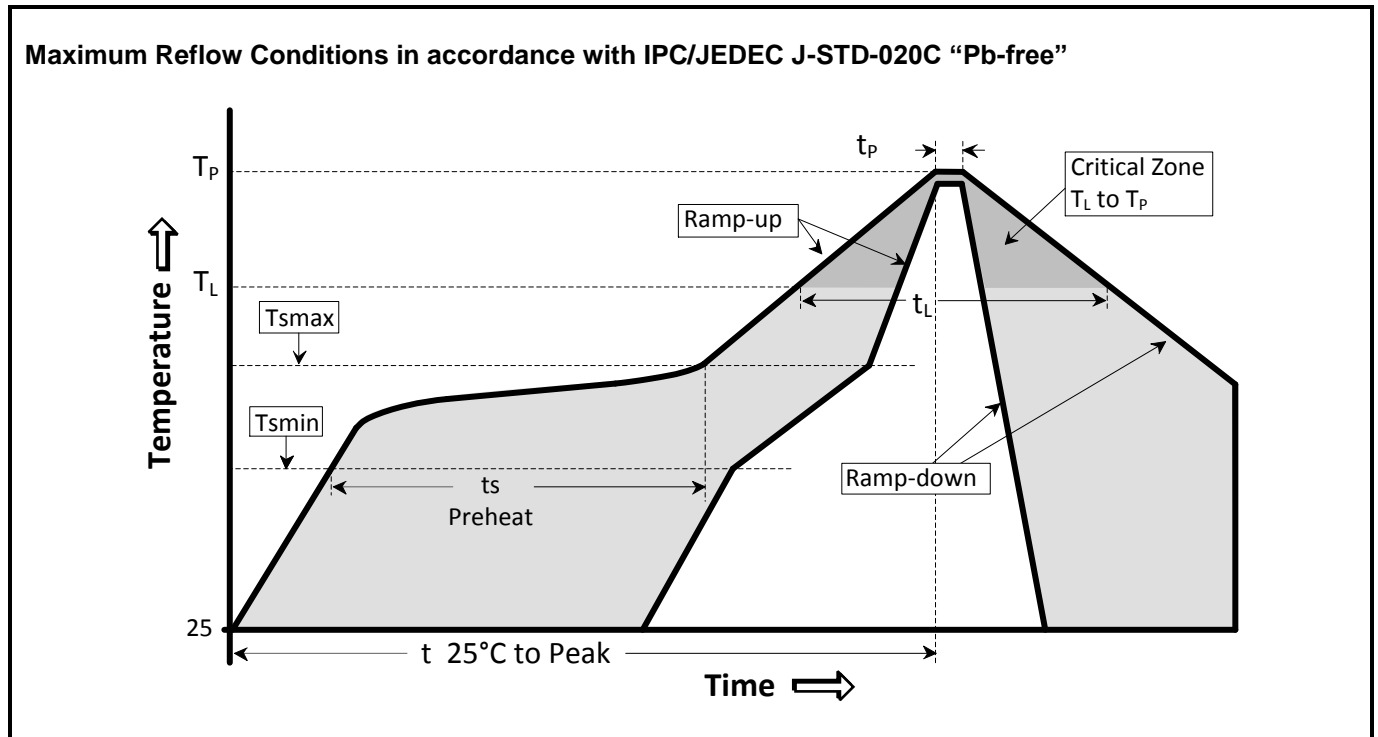
Parameter	Directive	Conditions	Value
Product weight (total)			140 mg
Storage temperature	MIL-O-55310	Store as bare product	-55 to +125°C
Moisture sensitivity level (MSL)	IPC/JEDEC J-STD-020D		MSL 1
FIT / MTBF			available on request

Terminal finish:



6. Application Information

6.1. Soldering Information



Temperature Profile	Symbol	Condition	Unit
Average ramp-up rate	($T_{S_{max}}$ to T_P)	3°C / second max	°C / s
Ramp down Rate	T_{cool}	6°C / second max	°C / s
Time 25°C to Peak Temperature	$T_{to-peak}$	8 minutes max	min
Preheat			
Temperature min	$T_{S_{min}}$	150	°C
Temperature max	$T_{S_{max}}$	200	°C
Time $T_{S_{min}}$ to $T_{S_{max}}$	t_s	60 – 180	sec
Soldering above liquidus			
Temperature liquidus	T_L	217	°C
Time above liquidus	t_L	60 – 150	sec
Peak temperature			
Peak Temperature	T_p	260	°C
Time within 5°C of peak temperature	t_p	20 – 40	sec

6.2. Handling Instructions for Quartz Crystal Units

The built-in Inverted Mesa AT-cut crystal consists of pure Silicon Dioxide in crystalline form. The cavity inside the package is evacuated and hermetically sealed in order for the crystal blank to function undisturbed from air molecules, humidity and other influences.

Shock and vibration:

Keep the crystal / module from being exposed to **excessive mechanical shock and vibration**. Micro Crystal guarantees that the crystal / module will bear a mechanical shock of 5000 g / 0.3 ms.

The following special situations may generate either shock or vibration:

Multiple PCB panels - Usually at the end of the pick & place process the single PCBs are cut out with a router. These machines sometimes generate vibrations on the PCB that have a fundamental or harmonic frequency close to the resonance frequency of the crystal unit. This might cause breakage of crystal blanks due to resonance. Router speed should be adjusted to avoid resonant vibration.

Ultrasonic cleaning - Avoid cleaning processes using ultrasonic energy. These processes can damage crystals due to mechanical resonance of the crystal blank.

Overheating, rework high temperature exposure:

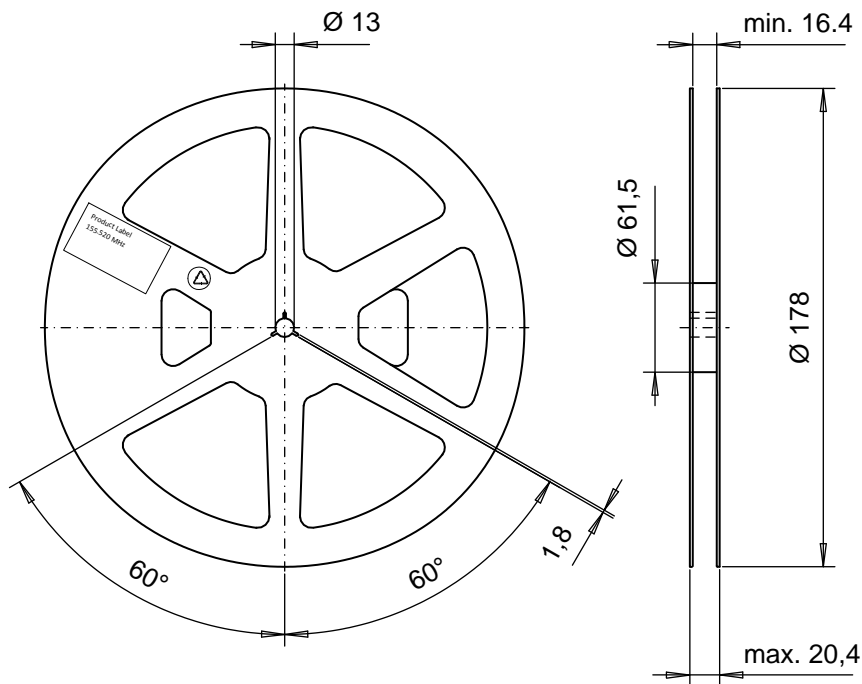
Avoid overheating the package. The package is sealed with a seal ring consisting of 80% Gold and 20% Tin. The eutectic melting temperature of this alloy is at 280°C. Heating the seal ring up to >280°C will cause melting of the metal seal which then, due to the vacuum, is sucked into the cavity forming an air duct. This happens when using hot-air-gun set at temperatures >300°C.

Use the following methods for rework:

- Use a hot-air- gun set at 270°C.
- Use 2 temperature controlled soldering irons, set at 270°C, with special-tips to contact all solder-joints from both sides of the package at the same time,

7. Packing & Shipping Information

Reel: 7" = 178 mm

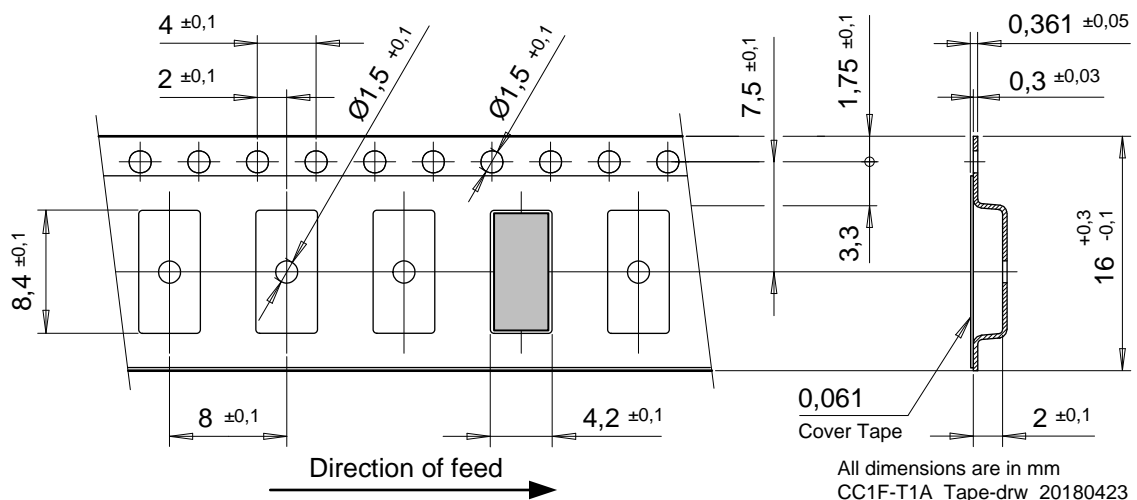


Carrier Tape:

Material: Polycarbonate

Width: 16 mm

Tape Leader and Trailer: Minimum length 300 mm



All dimensions are in mm
CC1F-T1A_Tape-drw_20180423

Cover Tape:

Tape: Polypropylene, 3M™ Universal Cover Tape (UCT)

Adhesive Type: Pressure sensitive, Synthetic Polymer

Thickness: 0.061 mm

Peel Method:

Medial section removal, both lateral stripes remain on carrier

8. Compliance Information

Micro Crystal confirms that the standard product Quartz Crystal Unit CC1F-T1A is compliant with “EU RoHS Directive” and “EU REACH Directives”.

Please find the actual Certificate of Conformance for Environmental Regulations on our website:

[CoC_Environment_CC&CM-Series.pdf](#)

9. Document Revision History

Date	Revision #	Revision Details
April 2018	1.0	First release

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